

Soldering Temperature	T _{sol}	260	
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NOTE2 (}Œ íu]vµš U ZX,XAđì•òì9

ELECTRICAL CHARACTERISTICS (Temperature = 25 Å C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V _F	I _F = 10mA	-	1.8	2.5	V
	Reverse Current	I _R	V _R = 6V	-	-	1	µA
	Input Capacitance	C _{IN}	V = 0V f = 1MHz	-	70	-	pF
Detector	Off-state Current	I _{OFF}	V _{OFF} = 100V	-	-	10	nA
	Output Capacitance	C _{OFF}	V = 0V f = 1MHz t < 1s	-	170	-	pF
	Trigger LED Current	I _{FT}	I _{ON} = 2A	-	0.35	1	mA
						-	mA
						1	=
							=
						-	=

ORDERING INFORMATION

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Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

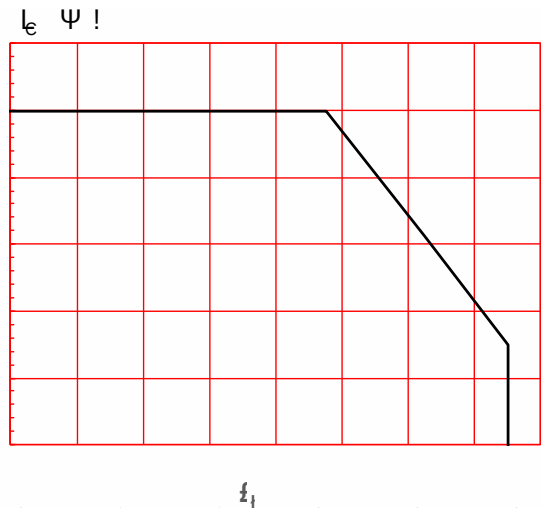


FIG.2: On-state Current vs. Ambient Temperature

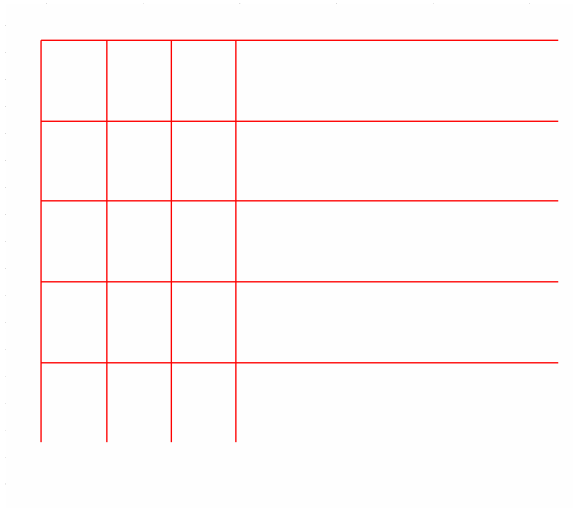


FIG.7: T_{ON},T_{OFF} VS. LED Forward Current

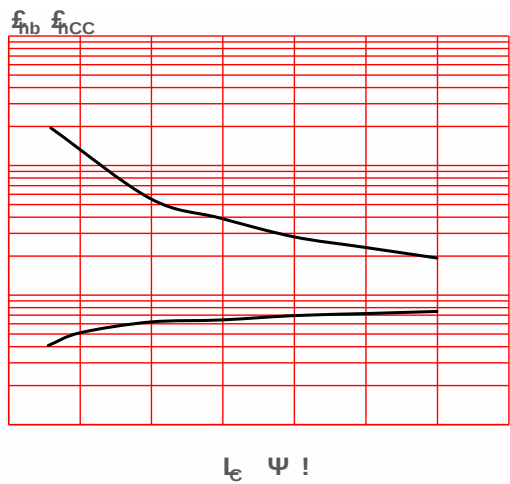
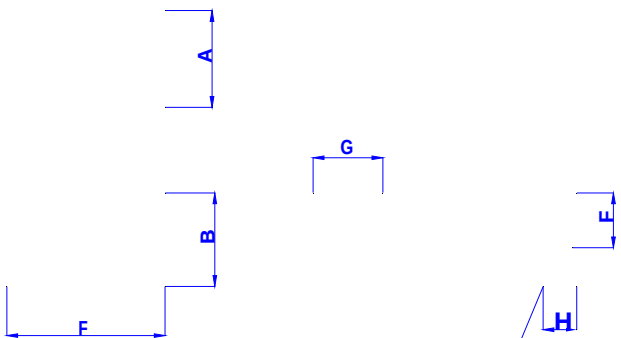


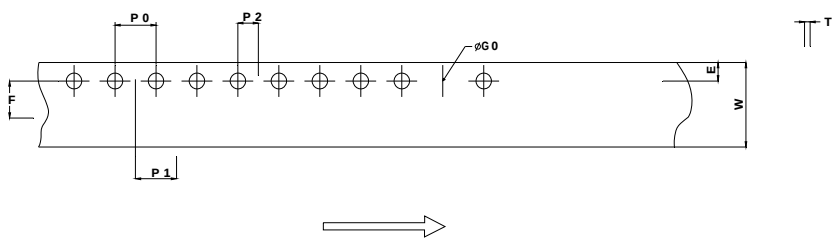
FIG.8: T_{ON},T_{OFF} VS. Ambient Temperature

Package Dimension (Unit: mm)



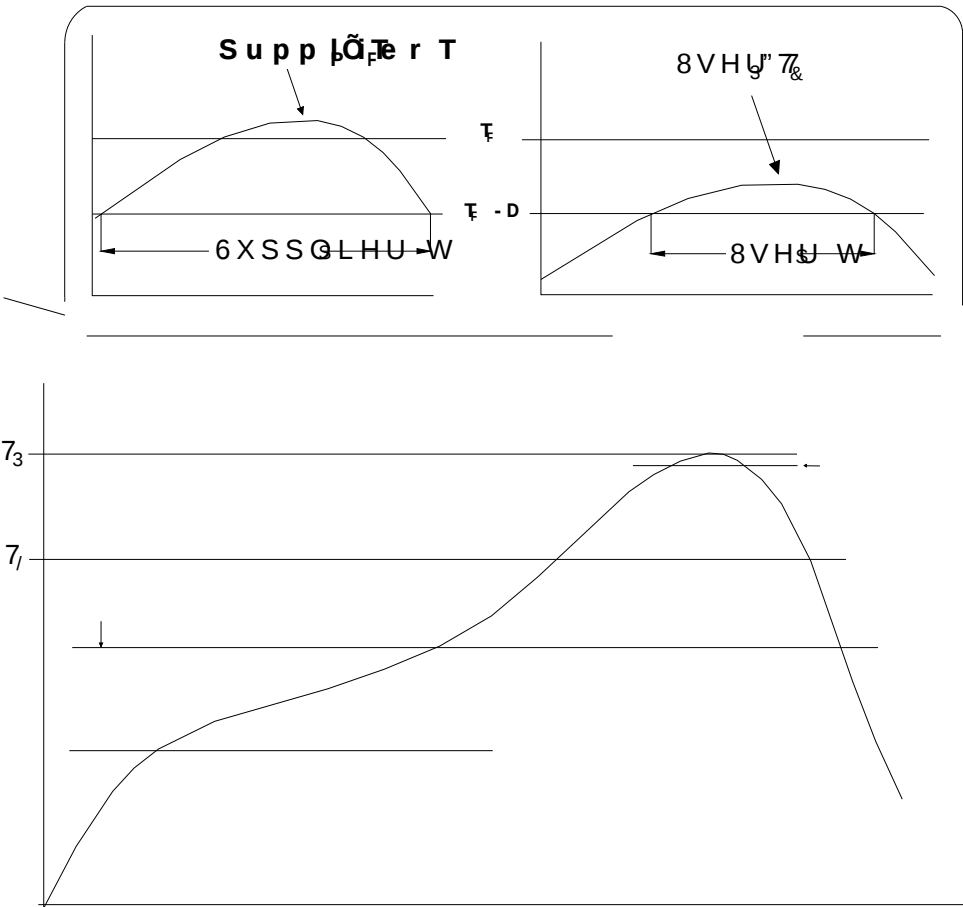
Re f B	G i m e n s i o n s							
	M i l l i m e t e r s							
	M i n	B T y p	B M M x B	M i n	B T y p	B M M x B	B M M x B	H n c O e s
A	1B30		1B70	0B0D1			0B067	
B	1BE0		2B30	0B07D			0B0E1	
F	3B20		3B60	0B126			0B142	
G	0B88		1B28	0B03D			0B0D0	
E	2B1D		2BDD	0B08D			0B100	
F	1B00		1B40	0B03E			0B0DD	
G	0B20		0B60	0B008			0B024	
H	0B6D		-	00				

CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



Ref	Dimensions								Notes	
	Millimeters									
	Min	Typ	Max	Min	Typ	Max	Min	Typ		Max
G0		1800	1860		0800	E0800	3			
P0	38E0	4800	4810	0810	40810	70816	1			
P1	38E0	4800	4810	0810	40810	70816	1			
P2	18E0	2800	2810	0800	7E080	7E080	3			
E	1860	1870	1880	0800	6E080	6E080	7			
F	3840	3800	3860	0810	40810	70816	1			
T	0820	0820	0830	0800	80801	80801	2			
W	7870	8800	8830	0830	30831	30832	7			

REFLOW INFORMATION



Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0 ~ 40 ℃ ;
Recommend storage humidity: < 60% ;
MSL level: MSL 3

Information furnished in this document is believed to be accurate and reliable. However, Jiangsu JieJie Microelectronics

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